

REMARKS

Claims 1, 3-5, 7 and 8 are pending in this application.

By this Amendment, claims 1 and 5 are amended for clarity and to incorporate the subject matter of claims 2 and 6, and claims 2 and 6 are canceled. Thus, no new matter is added by this Amendment.

I. Rejection Under 35 U.S.C. §103(a)

Claims 1-8 were rejected under 35 U.S.C. §103(a) over "admitted prior art" (Applicant's Fig. 5) in view of U.S. Patent Publication No. 2001/0015484 (Matsuura). This rejection is respectfully traversed.

Claim 1 recites an insulating sheet for hard disk device comprising an adhesive layer having adhesiveness exhibiting temperature higher than normal ambient temperature, wherein the adhesive layer is formed of polyester resin that does not contain a silicone component.

Claim 5 recites a hard disk device comprising an insulating sheet that includes an adhesive layer having adhesiveness exhibiting temperature higher than normal ambient temperature, wherein the adhesive layer is formed of polyester resin that does not contain a silicone component.

The Office Action asserts that Applicant's Admitted Prior Art, i.e., Applicant's Fig. 5 teaches all of the features of claims 1 and 5 except that the adhesive layer is not adhesive at normal ambient temperature but exhibiting adhesiveness when heated. The Office Action then asserts that Matsuura teaches using a variety of polyester/polyether based heat resistant resin compositions including those without a silicone component to provide improved adhesion/bonding between a variety of substrates/layers where the adhesion/bonding is performed under compression and heat treatment and the temperature of the heat treatment is higher than normal ambient temperature.

Contrary to the assertions made in the Office Action, the features of claims 1 and 5 are not taught or suggested by Applicant's Fig. 5 and/or Matsuura. By this amendment, it is clear that the present claims are directed to an insulating sheet for a hard disk device that includes the characteristic of an adhesive layer formed of polyester resin that does not contain a silicone component.

Matsuura discloses an adhesive that adheres a semiconductor to a light lead frame. However, Matsuura fails to disclose an adhesive and buffer layer including resin film that are appropriate for a hard disk device. Therefore, there is no motivation to combine the resin as disclosed by Matsuura with Applicant's admitted prior art.

Furthermore, Matsuura fails to disclose an adhesive that excludes silicone. Accordingly, even if one of ordinary skill in the art combined Matsuura with Applicant's admitted prior art, the claimed combination of features still would not be achieved, because the adhesive of Matsuura fails to exclude a silicone component.

For the foregoing reasons, Applicant submits that Applicant's admitted prior art, alone or in combination with Matsuura, fails to render obvious the subject matter of claims 1 and 5.

With respect to claims 3 and 7, these claims are not rendered obvious by Applicant's admitted prior art, alone or in combination with Matsuura, at least for the same reasons discussed above with respect to claims 1 and 5, respectively. Furthermore, nowhere does Applicant's admitted prior art or Matsuura teach or suggest that the resin film is polyethylene terephthalate having highly adhesiveness to the polyester resin and the adhesive strength is high, as recited in each of claims 3 and 7.

Applicant's admitted prior art, alone or in combination with Matsuura, also fails to render obvious the subject matter of claims 4 and 8. In particular, nowhere do these references teach or suggest that the buffer layer is formed of urethane foam and that it can be adhered to the resin film via adhesive formed of polyester resin.

For the foregoing reasons, Applicant submits that Applicant's admitted prior art, alone or in combination with Matsuura, fails to render obvious the subject matter of claims 1, 3-5, 7 and 8.

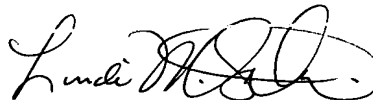
Withdrawal of the rejection is thus respectfully requested.

II. Conclusion

In view of the foregoing, it is respectfully submitted that this application is in condition for allowance. Favorable reconsideration and prompt allowance of the pending claims are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in even better condition for allowance, the Examiner is invited to contact the undersigned at the telephone number set forth below.

Respectfully submitted,



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